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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







Typical Applications

The HMC548LP3 / HMC548LP3E is ideal for:

- Automotive Telematics
- GPS Antenna Modules / Boosters
- Location Based Portables
- Satellite Navigation

Functional Diagram



HMC548LP3 / 548LP3E

SiGe HBT MMIC LOW NOISE AMPLIFIER, 1.2 - 3.0 GHz

Features

Single Supply: Vcc = +3 to +5V Low Noise Figure: 1.3 dB High Output IP3: +21 dBm No External Matching Required External Filter Access 3x3 mm Leadless SMT Package

General Description

The HMC548LP3 & HMC548LP3E are comprised of two internally matched SiGe HBT MMIC low noise amplifier stages housed in 3x3 mm leadless SMT packages. The unique topology of the HMC548LP3 & HMC548LP3E provides interstage access allowing the designer to place a bandpass filter between the two amplifier stages. This filtering approach enables the receiver to reject nearby blocking signals such as those emitted from cellular and 3G hand-helds, without incurring the noise figure degradation associated with a high rejection pre-filter. When combined with the appropriate interstage bandpass filter, this LNA can be used as a receiver pre-amplifier in various applications from 1.2 to 3 GHz. Evaluation boards are available with or without a GPS L1 (1575 MHz) band pass filter.

Electrical Specifications, $T_{A} = +25^{\circ}C^{*}$

Parameter	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
Frequency Range	15		575			MHz	
Vcc	+3			+5			V
Gain	20	23		23	26		dB
Gain Variation Over Temperature		0.04	0.05		0.04	0.05	dB/°C
Noise Figure		1.6	1.9		1.3	1.6	dB
Input Return Loss		8			8		dB
Output Return Loss		14			16		dB
Output 1 dB Compression (P1dB)		8			11		dBm
Saturated Output Power (Psat)		10.5			12		dBm
Output Third Order Intercept (IP3)		13			21		dBm
Supply Current (Icc)		10	15		21	30	mA

* All measurements include external 1.57 - 1.6 GHz (GPS L1) band pass filter connected between pin 4 & pin 9.

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Gain & Return Loss



Input Return Loss vs. Temperature [1]



Reverse Isolation vs. Temperature 11



Gain vs. Temperature 💷



HMC548LP3 / 548LP3E

SiGe HBT MMIC LOW NOISE

AMPLIFIER, 1.2 - 3.0 GHz

Output Return Loss vs. Temperature



Noise Figure vs. Temperature [1]



[1] Measurement includes external 1.57 - 1.6 GHz (GPS L1) band pass filter connected between pin 4 and pin 9. Vcc = +5V.

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P1dB vs. Temperature [1]



Output IP3 vs. Temperature [1]



Gain vs. Temperature^[2]



HMC548LP3 / 548LP3E

SiGe HBT MMIC LOW NOISE AMPLIFIER, 1.2 - 3.0 GHz

Psat vs. Temperature [1]



Broadband Gain & Return Loss^[2]



Input Return Loss vs. Temperature^[2]



Measurement includes external 1.57 - 1.6 GHz (GPS L1) band pass filter connected between pin 4 and pin 9. Vcc = +5V.
Measurement includes external 50 Ohm line between pin 4 and pin 9. Vcc = +5V.

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Output Return Loss vs. Temperature^[2]



Noise Figure vs. Temperature [2]



Psat vs. Temperature [2] 20 15 PSAT (dBm) 10 +25 C +85 C -40 C 5 0 0.5 1 1.5 2 2.5 3 3.5 FREQUENCY (GHz)

HMC548LP3 / 548LP3E

SiGe HBT MMIC LOW NOISE AMPLIFIER, 1.2 - 3.0 GHz







Output IP3 vs. Temperature^[2]



[2] Measurement includes external 50 Ohm line between pin 4 and pin 9. Vcc = +5V.

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Small Signal Parameters Input Stage [3] 10 5 0 RESPONSE (dB) -5 -10 -15 -20 -25 S21 S11 S22 S12 -30 - -- --35 -40 0.5 1.5 2 2.5 3 3.5 4 1 FREQUENCY (GHz)

P1dB Individual Stages [3]





[3] Vcc = +5V.

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SiGe HBT MMIC LOW NOISE AMPLIFIER, 1.2 - 3.0 GHz



Noise Figure Individual Stages ^[3]





Gain & Return Loss^[4]



Input Return Loss vs. Temperature [4]



Reverse Isolation vs. Temperature^[4]



HMC548LP3 / 548LP3E

SiGe HBT MMIC LOW NOISE AMPLIFIER, 1.2 - 3.0 GHz

30 26 22 GAIN (dB) 18 +25C +850 -400 14 10 1.56 1.565 1.57 1.575 1.58 1.585 1.59 FREQUENCY (GHz)

Gain vs. Temperature [4]

Output Return Loss vs. Temperature^[4]



Noise Figure vs. Temperature [4]



[4] Measurement includes external 1.57 - 1.6 GHz (GPS L1) band pass filter connected between pin 4 and pin 9. Vcc = +3V.

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P1dB (dBm)

5

0

1.56

1.565

P1dB vs. Temperature [4]



SiGe HBT MMIC LOW NOISE AMPLIFIER, 1.2 - 3.0 GHz

10 Psat (dBm) 5 +25C +85C +25C -40C +85C . . . -40C ٥ 1.56 1.575 1.58 1.585 1.59 1.565 1.57 1.575 1.58 1.585 1.59 1.57 FREQUENCY (GHz) FREQUENCY (GHz) Output IP3 vs. Temperature^[4] 20 15

Psat vs. Temperature^[4]



Absolute Maximum Ratings

Drain Bias Voltage (Vcc)	+7.0 Vdc
RF Input Power (RFIN)	-5 dBm
Junction Temperature	150 °C
Continuous Pdiss (T = 85 °C) (derate 14 mW/°C above 85 °C)	0.942 W
Thermal Resistance (junction to ground paddle)	69 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1B

Typical Supply Current vs. Vcc

Vcc (Vdc)	Icc (mA)		
3.0	10		
4.5	17		
5.0	21		
5.5	24		



[4] Measurement includes external 1.57 - 1.6 GHz (GPS L1) band pass filter connected between pin 4 and pin 9. Vcc = +3V.

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HMC548LP3 / 548LP3E

SiGe HBT MMIC LOW NOISE AMPLIFIER, 1.2 - 3.0 GHz



Outline Drawing







- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
- PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC548LP3	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	548 XXXX
HMC548LP3E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	<u>548</u> XXXX

[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	RFIN1	This pin is DC coupled and matched to 50 Ohms from 1.2 to 2.0 GHz. An off chip blocking capacitor is required.	RFIN1 O
2, 3, 5 - 8,10, 11, 13, 14, 16	GND	These pins and package ground paddle must be connected to RF/DC ground.	
4	RFOUT1	This pin is AC coupled and matched to 50 Ohms from 1.2 - 2 GHz.	├○ RFOUT1
9	RFIN2	This pin is DC coupled and matched to 50 Ohms from 1.2 to 2.0 GHz. An off chip blocking capacitor is required.	RFIN2 O
12	RFOUT2	This pin is AC coupled and matched to 50 Ohms from 1.2 - 2 GHz.	
15	Vcc	Power supply voltage for the amplifier. External bypass capacitors of 1,000pF and 18,000 pF are required.	- - -

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HMC548LP3 / 548LP3E

SiGe HBT MMIC LOW NOISE AMPLIFIER, 1.2 - 3.0 GHz





v03.1011

List of Material for Evaluation PCB 114254^[1]

Item	Description
J1, J2	PCB Mount SMA Connector
J3, J4	DC Pin
C1, C2	150 pF Capacitor, 0402 Pkg.
C3	1000 pF Capacitor, 0402 Pkg.
C4	18,000 pF Capacitor, 0402 Pkg.
U1	HMC548LP3 / HMC548LP3E Amplifier
U2	Filter, Amotech AMOBP1575P02-A1 2.5 dB loss @ 1575 MHz
PCB [2]	110980 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed ground paddle should be connected directly to the ground plane similar to that shown above. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

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HMC548LP3 / 548LP3E

SiGe HBT MMIC LOW NOISE AMPLIFIER, 1.2 - 3.0 GHz



Wideband (No Filter) Evaluation PCB

v03.1011



List of Material for Evaluation PCB 113979^[1]

Item	Description
J1, J2	PCB Mount SMA Connector
J3, J4	DC Pin
C1, C2	150 pF Capacitor, 0402 Pkg.
С3	1000 pF Capacitor, 0402 Pkg.
C4	18,000 pF Capacitor, 0402 Pkg.
U1	HMC548LP3 / HMC548LP3E Amplifier
PCB [2]	113977 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed ground paddle should be connected directly to the ground plane similar to that shown above. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request. AMPLIFIERS - LOW NOISE - SM1